

FIG. 1

TITLE: METHODS FOR MANUFACTURING PRINTED CIRCUIT BOARDS USING A PARTIAL PRINTING PROCESS AND APPARATUS

INVENTOR'S NAME: Dudi Amir

DKT. #. 884.147US2

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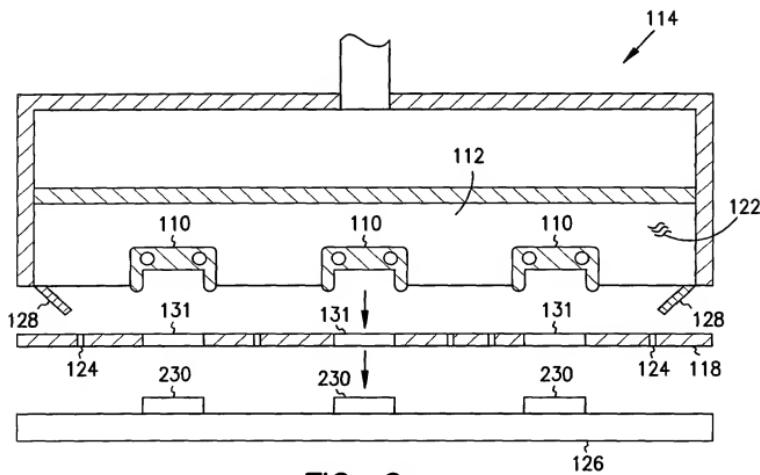


FIG. 2

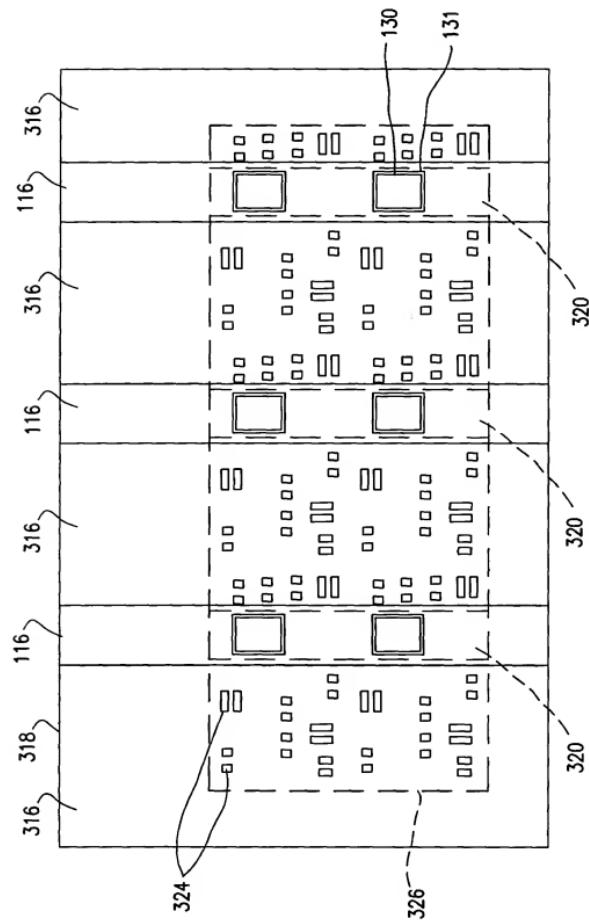


FIG. 3

TITLE: METHODS FOR MANUFACTURING PRINTED CIRCUIT BOARDS USING A PARTIAL PRINTING PROCESS AND APPARATUS

INVENTORS NAME: Dudi Amir

DKI #: 884,147US2

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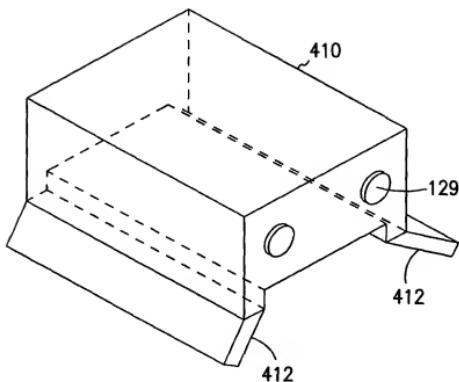


FIG. 4

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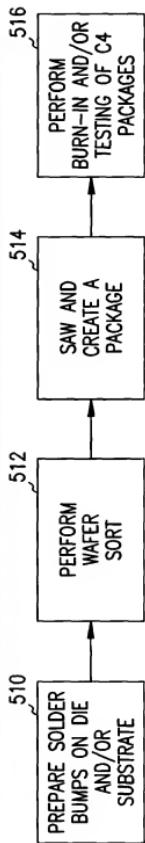
CONTROLLED COLLAPSE CHIP CONNECTION PACKAGE PROCESS (C4 PACKAGE PROCESS)

FIG. 5A (Prior Art)

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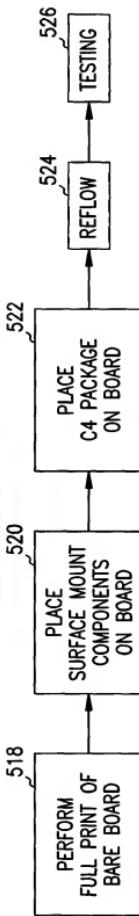
FULL PRINTING AND PLACEMENT PROCESS

FIG. 5B (Prior Art)

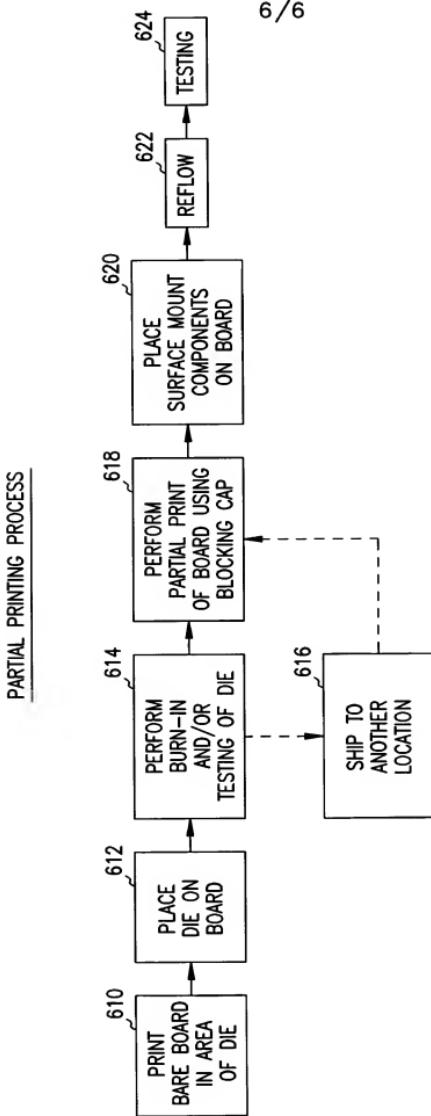


FIG. 6